

MECHANICAL CASE OUTLINE

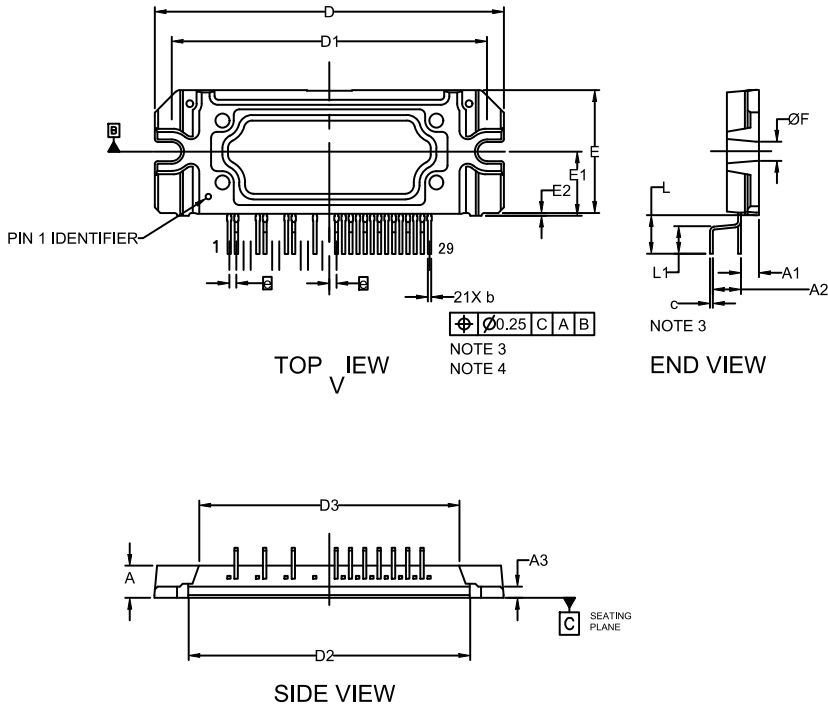
PACKAGE DIMENSIONS

ON Semiconductor®



SIP29 62x21.8FP-1 CASE 127EZ ISSUE O

DATE 07 MAY 2018



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b and c APPLY TO THE PLATED LEADS AND ARE MEASURED BETWEEN 1.00 AND 2.00 FROM THE LEAD TIP.
4. POSITION OF THE LEAD IS DETERMINED AT THE ROOT OF THE LEAD WHERE IT EXITS THE PACKAGE BODY.
5. MISSING PINS ARE 3,4,7,8,11,12,14 AND 15.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	5.20	5.70	6.20
A1	2.70	3.20	3.70
A2	4.50	5.00	5.50
A3	1.50	2.00	2.50
b	0.55	0.60	0.80
c	0.45	0.50	0.70
D	61.50	62.00	62.50
D1	55.50	56.00	56.50
D2	49.50	50.00	50.50
D3	45.70	46.20	46.70
E	21.8 REF		
E1	11.4 REF		
E2	0.00	0.50	1.00
e	1.27 BSC		
F	2.90	3.40	3.90
L	6.30	6.80	7.30
L1	3.80	4.30	4.80

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